DMC 60C51/31

CMOS SINGLE-COMPONENT 8-BIT MICROCOMPUTER

☐ FEATURES

- ○ 8 bit CPU optimized for control applications.
- ○ Power control modes.
- ○ Pin-to-pin compatible with intel's 80C51/ 80C31
- ○ 60C51 Low power mask programmable ROM
- ○ 60C31 Low power CPU only
- ○ 64K Program Memory Space, Data Memory space
- ○ 32 programmable I/O Lines.
- ○ Two 16 Bit Timer/counters.
- ○ High performance CMOS process.
- ○ 5 interrupt sources.
- ○ 2 Level Programmable serial port.
- ○ 3.5 to 12MHz @ 5V $\pm$ 20%

☐ MAXIMUM RATINGS

- ○ Ambient temperature under Bias ; $0°C \sim +70°C$
- ○ Storage temperature ; $-65°C \sim +150°C$
- ○ Voltage on any pin to Vss ; $-0.5V \sim Vcc + 0.5V$
- ○ Maximum I_{OL} per I/O pin ; 15mA
- ○ Power dissipation ; 1Watt

40DIP Unit : mm

44PLCC Unit : mm
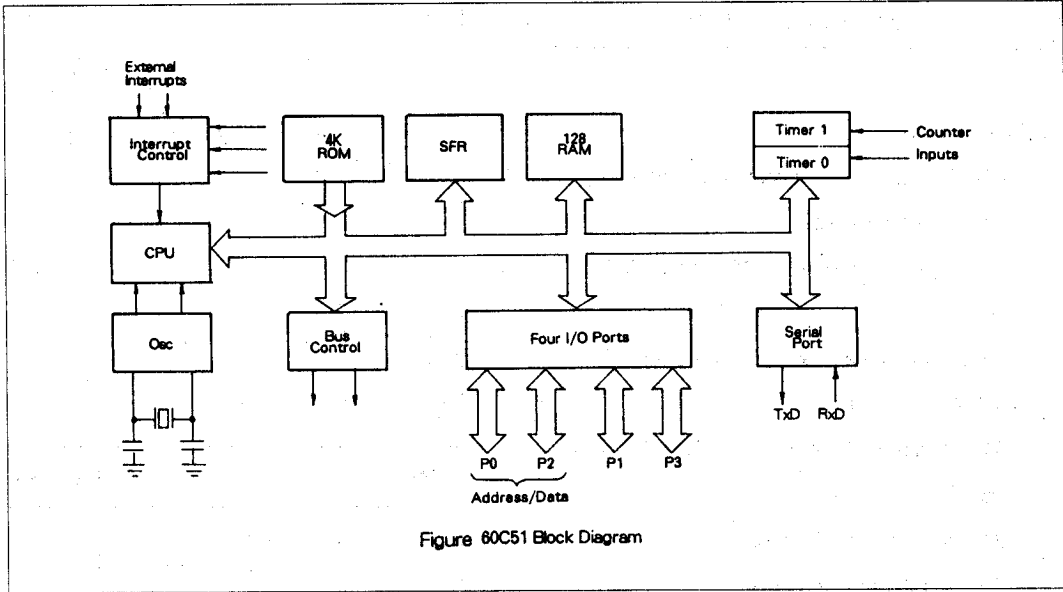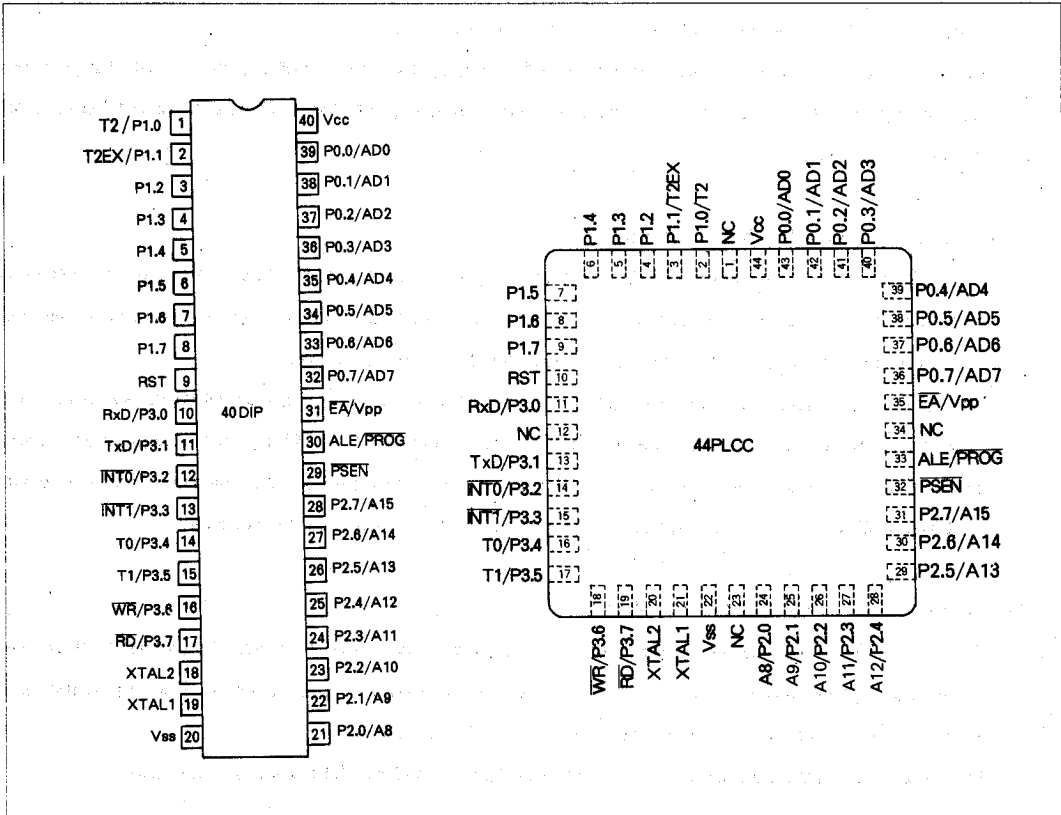
☐ BLOCK DIAGRAM

Figure 60C51 Block Diagram

☐ DESCRIPTION

The DAEWOO 60C31/60C51 is a high-performance micro controller fabricated with DAEWOO high-density CMOS technology. The DAEWOO CMOS technology combines the high speed and density characteristics of MOS with the low power attributes of CMOS.

The 60C51 contains a 4K×8 ROM, a 128×8 RAM, 32 I/O lines, two 16-bit counter/timers, a five-source, two-priority level nested interrupt structure, a serial I/O port for either multi-processor communication, I/O expansion or full duplex UART, and on-chip oscillator and clock circuits.

In addition, the device has tow software selectable modes of power reduction idle mode and powerdown mode. The idle mode freezes the CPU while allowing the RAM, timers, serial port, and interrupt system to continue functioning.

☐ PIN CONFIGURATION

```
40DIP
T2/P1.0    [1]        [40] Vcc
T2EX/P1.1  [2]        [39] P0.0/AD0
P1.2       [3]        [38] P0.1/AD1
P1.3       [4]        [37] P0.2/AD2
P1.4       [5]        [36] P0.3/AD3
P1.5       [6]        [35] P0.4/AD4
P1.6       [7]        [34] P0.5/AD5
P1.7       [8]        [33] P0.6/AD6
RST        [9]        [32] P0.7/AD7
RxD/P3.0   [10]       [31] EA/Vpp
TxD/P3.1   [11]       [30] ALE/PROG
INT0/P3.2  [12]       [29] PSEN
INT1/P3.3  [13]       [28] P2.7/A15
T0/P3.4    [14]       [27] P2.6/A14
T1/P3.5    [15]       [26] P2.5/A13
WR/P3.6    [16]       [25] P2.4/A12
RD/P3.7    [17]       [24] P2.3/A11
XTAL2      [18]       [23] P2.2/A10
XTAL1      [19]       [22] P2.1/A9
Vss        [20]       [21] P2.0/A8
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44PLCC

P1.5 [7] ... [39] P0.4/AD4
P1.6 [8] ... [38] P0.5/AD5
P1.7 [9] ... [37] P0.6/AD6
RST [10] ... [36] P0.7/AD7
RxD/P3.0 [11] ... [35] EA/Vpp
NC [12] ... [34] NC
TxD/P3.1 [13] ... [33] ALE/PROG
INT0/P3.2 [14] ... [32] PSEN
INT1/P3.3 [15] ... [31] P2.7/A15
T0/P3.4 [16] ... [30] P2.6/A14
T1/P3.5 [17] ... [29] P2.5/A13

Top pins: P1.4, P1.3, P1.2, P1.1/T2EX, P1.0/T2, NC, Vcc, P0.0/AD0, P0.1/AD1, P0.2/AD2, P0.3/AD3

Bottom pins: WR/P3.6, RD/P3.7, XTAL2, XTAL1, Vss, NC, A8/P2.0, A9/P2.1, A10/P2.2, A11/P2.3, A12/P2.4

☐ PIN DESCRIPTION

Vcc : PIN 40(40DIP), PIN44(44PLCC)

Supply voltage during normal, Idle and Power down operations.

Vss : PIN20(40DIP), PIN22(44PCC)

Circuit ground.

Port 0 : PIN32~39(40DIP), PIN36~43(44PLCC)

Port 0 is an 8-bit open drain bi-directional I/O port. Port 0 pins that have 1's written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed low-order address and data bus during accesses to external Program and Data memory.

In this application it uses strong internal pullups when emitting 1's

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☐ PIN DESCRIPTION (Continued)

Port 1 : PIN 1~8(40DIP), PIN2~9(44PLCC)

    Port 1 is an 8-bit bidirectional I/O port with internal pullups.

    Port 1 pins that have 1s written to them are pulled high by the internal pullups, and in that state can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current because of the internal pullups.

Port 2 : PIN 21~28(40DIP), PIN24~31(44PLCC)

    Port 2 is an 8-bit bidirectional I/O port with internal pullups. Port 2 pins that have 1's written to them are pulled high by the internal pullups, and in that state can be used as input. As inputs, Port 2 pins that are externally being pulled low will source current because of the internal pullups.

    Port 2 emits the high-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses(MOVX @ DPTR). In this application it uses strong internal pullups when emitting 1's. During accesses to external Data Memory that use 8-bit addresses(MOVX @ Ri), Port2 emits the contents of the P2 Special Function Register.

Port 3 : PIN 10~17(40DIP), PIN 13~19(44PLCC)

    Port 3 is an 8-bit bidirectional I/O port with internal pullups. Port 3 pins that have 1s written to them are pulled high by the internal pullups, and in that state can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current because of the pullups.

    Port 3 also serves the function of various special feature of the MCS-51 Family, as listed below :

Port PIN	PIN NO.	Alternate Function
P 3.0	10	RxD(Serial input port)
P 3.1	11	TxD(Serial output port)
P 3.2	12	$\overline{INT0}$(external interrupt 0)
P 3.3	13	$\overline{INT1}$(external interrupt 1)
P 3.4	14	T0(Timer 0 external input)
P 3.5	15	T1(Timer 1 external input)
P 3.6	16	$\overline{WR}$(external data memory write strobe)
P 3.7	17	$\overline{RD}$(external data memory read strobe)

RST : PIN9(40DIP), PIN10(44PLCC)

    Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

    An internal diffused resistor to Vss permits Power-On reset using only an external capacitor to Vcc.

☐ PIN DESCRIPTION (Continued)

ALE : PIN30(40DIP), PIN33(44PLCC)

Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, and may be used for external timing or clocking purposes.

Note; however, that one ALE pulse is skipped during each access to external Data Memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX instruction. Otherwise, the pin is weakly pulled high.

$\overline{PSEN}$: PIN29(40DIP), PIN32(44PLCC)

Program Store Enable is the read strobe to external Program Memory. When the 60C51 is executing code from external Program Memory, $\overline{PSEN}$ is activated twice each machine cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external Data Memory. $\overline{PSEN}$ is not activated during fetches from internal program memory.

$\overline{EA}$: PIN31(40DIP), PIN35(44PLCC)

External Access enable. $\overline{EA}$ must be strapped to Vss in order to enable the device to fetch code from external Program Memory locations starting at 0000H up to FFFFH. If $\overline{EA}$ is strapped to Vcc the device executes from internal Program Memory unless the program counter contains an address greater than 0FFFH.

XTAL1 : PIN19(40DIP), PIN21(44PLCC)

Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
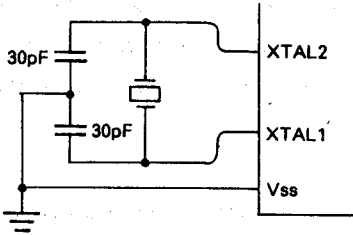
NC : PIN1, 12, 23, 34(44PLCC)

Non connection pins.

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☐ PIN DESCRIPTION (Continued)

XTAL2 : PIN18(40DIP), PIN20(44PLCC)

Output from the inverting oscillator amplifier

○ Crystal Oscillator

```
30pF ═╣        ┌── XTAL2
        ▭
      ═╣ 30pF  └── XTAL1

                   Vss
                  ⏚
```

☐ IDLE MODE

In the Idle mode, the CPU puts itself to sleep while all the on chip peripherals stay active. The instruction that invokes the Idle mode is the last instruction executed in the normal operating mode before Idle mode is activated. The content of the on-chip RAM and all the Special Function Registers remain intact during this mode. The Idle mode can be terminated either by any enabled interrupt, at which time the process is picked up at the interrupt service routine and continued, or by a hardware reset which starts the processor the same as a power on reset.

☐ POWER DOWN MODE

In the Power Down mode the oscillator is stopped, and the instruction that invokes Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power Down mode is terminated.

The only exit from Power Down is a hardware reset. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before Vcc is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

POWER DOWN MODE (Continued)

The control bits for the reduced power modes are in the Special Function Register PCON.

Table. Status of the external pins during Idle and Power Down modes.

Mode	Program Memory	ALE	PSEN	RORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power Down	Internal	0	0	Data	Data	Data	Data
Power Down	External	0	0	Float	Data	Data	Data

ELECTRICAL CHARACTERISTICS (DC)

($T_a = 0°C \sim 70°C$ or $-40°C \sim 85°C$, Vcc = 5V ± 20%, Vss = 0V)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS MIN	LIMITS TYP	LIMITS MAX	UNIT
V_{IL}	Input low voltage, except $\overline{EA}$		−0.5		0.2Vcc−0.1	V
V_{IL1}	Input low voltage to $\overline{EA}$		0		0.2Vcc−0.3	V
V_{IH}	Input high voltage, except XTAL1, RST		0.2Vcc+0.9		Vcc+0.5	V
V_{IH1}	Input high voltage to XTAL1, RST		0.7Vcc		Vcc+0.5	V
V_{OL}	Output low voltage to ports 1, 2, 3	$I_{OL} = 1.6mA$			0.45	V
V_{OL1}	Output low voltage to port 0, ALE, $\overline{PSEN}$	$I_{OL} = 3.2mA$			0.45	V
V_{OH}	Output high voltage to ports 1, 2, 3, ALE, $\overline{PSEN}$	$I_{OH} = -60\mu A$	2.4			V
		$I_{OH} = -25\mu A$	0.75Vcc			V
		$I_{OH} = -10\mu A$	0.9Vcc			V
V_{OH1}	Output high voltage (port 0 in external bus mode)	$I_{OH} = -800\mu A$	2.4			V
		$I_{OH} = -300\mu A$	0.75Vcc			V
		$I_{OH} = -80\mu A$	0.9Vcc			V
I_{IL}	Logical 0 input current to ports 1, 2, 3	$V_{IN} = 0.45V$			−50	μA
I_{TL}	Logical 1-to-0 transition current to ports 1, 2, 3	$V_{IN} = 2V$			−650	μA
I_{LI}	Input leakage current to port 0, $\overline{EA}$	$0.45 < V_{IN} < V_{CC}$			±10	μA
I_{CC}	Power supply current	See note1				
	Active mode @ 12MHz			11	20	mA
	Idle mode @ 12MHz			1.7	5	mA
	Power-down mode			5	50	μA
R_{RST}	Internal reset pull-down resistor		50		150	kohm
C_{10}	Pin capacitance				10	pF

Note : 1. See figure 8 through 11 for Icc test conditions. Minimum Vcc for Power Down is 2V.
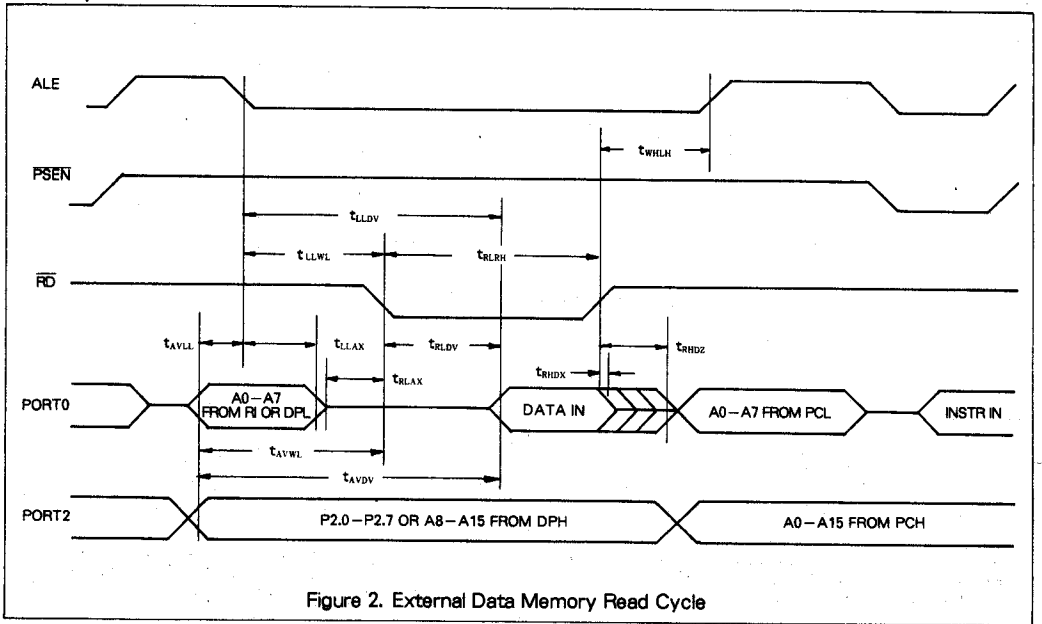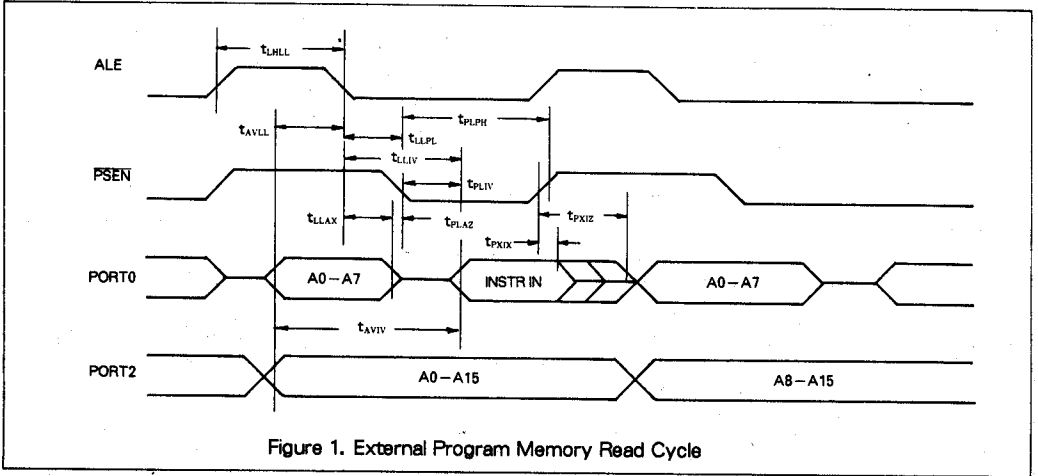
☐ ELECTRICAL CHARACTERISTICS (AC)

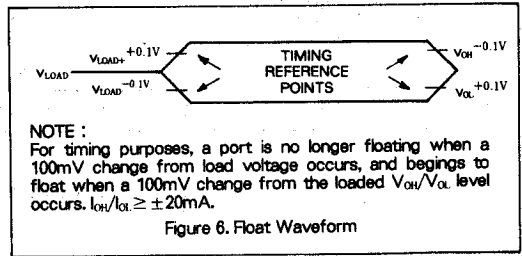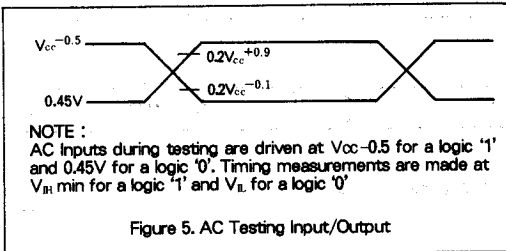($T_a = 0°C$ or $-40°C \sim 85°C$, $Vcc = 5V \pm 20\%$, $V_{ss} = 0V$)

SYMBOL	FIGURE	PARAMETER	12MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{\alpha\alpha}$		Oscillator frequency : Speed Versions 60C31/51			3.5	12	MHz
t_{LHLL}	1	ALE pulse width	127		$2t_{\alpha\alpha}-40$		ns
t_{AVLL}	1	Address valid to ALE low	28		$t_{\alpha\alpha}-55$		ns
t_{LLAX}	1	Address hold after ALE low	48		$t_{\alpha\alpha}-35$		ns
t_{LLIV}	1	ALE low to valid instruction in		234		$4t_{\alpha\alpha}-100$	ns
t_{LLPL}	1	ALE low to $\overline{PSEN}$ low	43		$t_{\alpha\alpha}-40$		ns
t_{PLPH}	1	$\overline{PSEN}$ pulse width	205		$3t_{\alpha\alpha}-45$		ns
t_{PLIV}	1	$\overline{PSEN}$ low to valid instruction in		145		$3t_{\alpha\alpha}-105$	ns
t_{PXIX}	1	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	1	Input instruction float after $\overline{PSEN}$		59		$t_{\alpha\alpha}-25$	ns
t_{AVIV}	1	Address to valid instruction in		312		$5t_{\alpha\alpha}-105$	ns
t_{PLAZ}	1	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	2, 3	$\overline{RD}$ pulse width	400		$6t_{\alpha\alpha}-100$		ns
t_{WLWH}	2, 3	$\overline{WR}$ pulse width	400		$6t_{\alpha\alpha}-100$		ns
t_{RLDV}	2, 3	$\overline{RD}$ low to valid data in		252		$5t_{\alpha\alpha}-165$	ns
t_{RHDX}	2, 3	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	2, 3	Data float after $\overline{RD}$		97		$2t_{\alpha\alpha}-70$	ns
t_{LLDV}	2, 3	ALE low to valid data in		517		$8t_{\alpha\alpha}-150$	ns
t_{AVDV}	2, 3	Address to valid data in		585		$9t_{\alpha\alpha}-165$	ns
t_{LLWL}	2, 3	ALE low to $\overline{RD}$ or $\overline{WR}$ low	200	300	$3t_{\alpha\alpha}-50$	$3t_{\alpha\alpha}+50$	ns
t_{AVWL}	2, 3	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	203		$4t_{\alpha\alpha}-130$		ns
t_{QVWX}	2, 3	Data valid to $\overline{WR}$ transition	23		$t_{\alpha\alpha}-60$		ns
t_{WHQX}	2, 3	Data hold after $\overline{WR}$	33		$t_{\alpha\alpha}-50$		ns
t_{RLAZ}	2, 3	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	2, 3	$\overline{RD}$ or $\overline{WR}$ high to ALE high	43	123	$t_{\alpha\alpha}-40$	$t_{\alpha\alpha}+40$	ns
External Clock							
t_{CHCX}	4	High time	20		20		ns
t_{CLCX}	4	Low time	20		20		ns
t_{CLCH}	4	Rise time		20		20	ns
t_{CHCL}	4	Fall time		20		20	ns

☐ **TIMING DIAGRAM**

Figure 1. External Program Memory Read Cycle

Figure 2. External Data Memory Read Cycle

☐ TIMING DIAGRAM (Continued)

Figure 3. External Data Memory Write Cycle

Figure 4. External Clock Drive

NOTE :
AC Inputs during testing are driven at $V_{CC}-0.5$ for a logic '1' and 0.45V for a logic '0'. Timing measurements are made at V_{IH} min for a logic '1' and V_{IL} for a logic '0'

Figure 5. AC Testing Input/Output

NOTE :
For timing purposes, a port is no longer floating when a 100mV change from load voltage occurs, and begins to float when a 100mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OH}/I_{OL} \geq \pm 20mA$.

Figure 6. Float Waveform

☐ TIMING DIAGRAM (Continued)

FREQ AT XTAL1

Figure 7. I_{CC} vs. FREQ
Valid only within frequency specifications
of the device under test
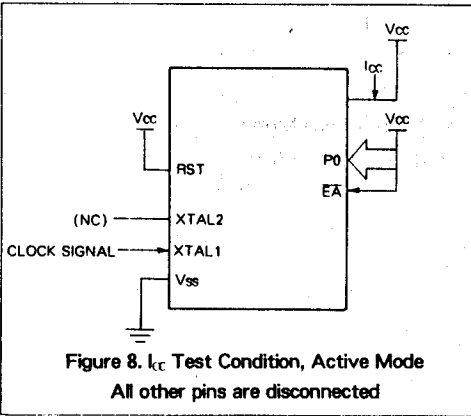
Figure 8. I_{CC} Test Condition, Active Mode
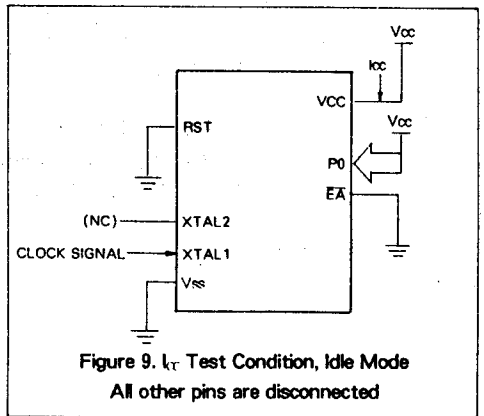All other pins are disconnected

Figure 9. I_{LT} Test Condition, Idle Mode
All other pins are disconnected
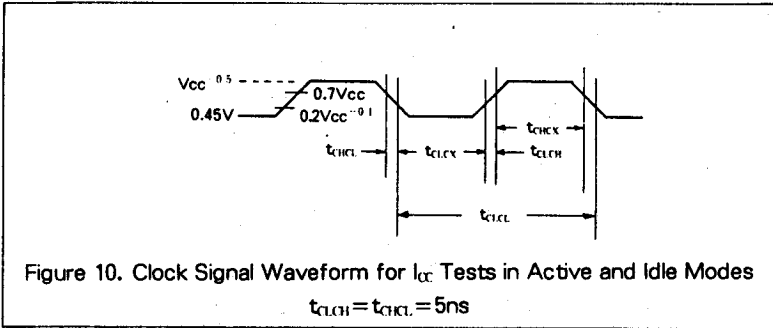
☐ TIMING DIAGRAM (Continued)

Figure 10. Clock Signal Waveform for I_{cc} Tests in Active and Idle Modes
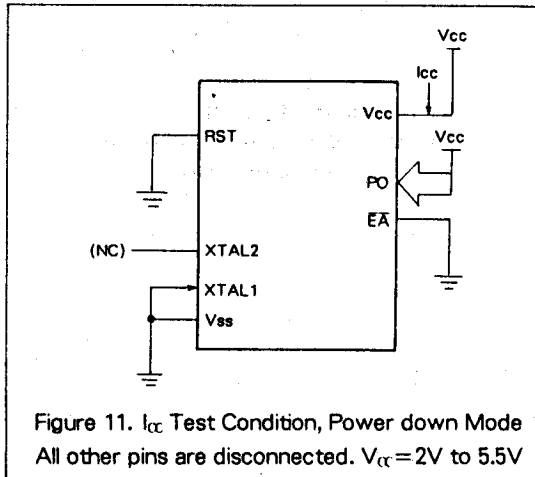$t_{CLCH} = t_{CHCL} = 5ns$

Figure 11. I_{cc} Test Condition, Power down Mode
All other pins are disconnected. $V_{cc} = 2V$ to $5.5V$